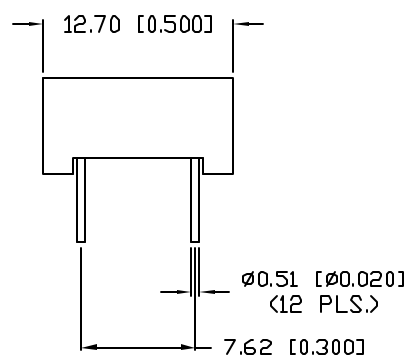
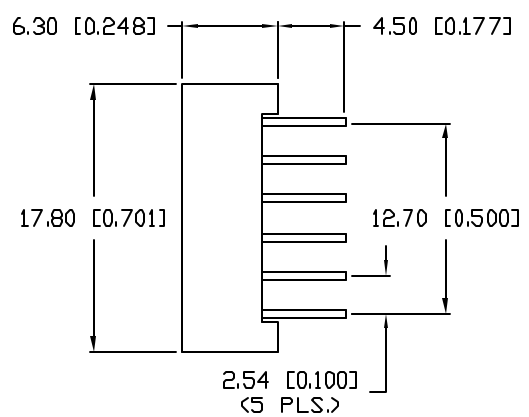
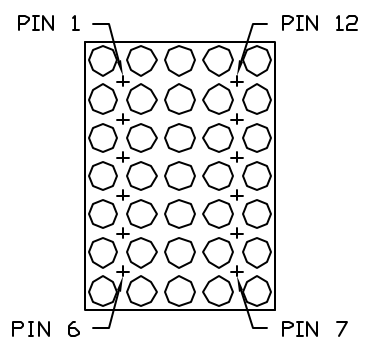


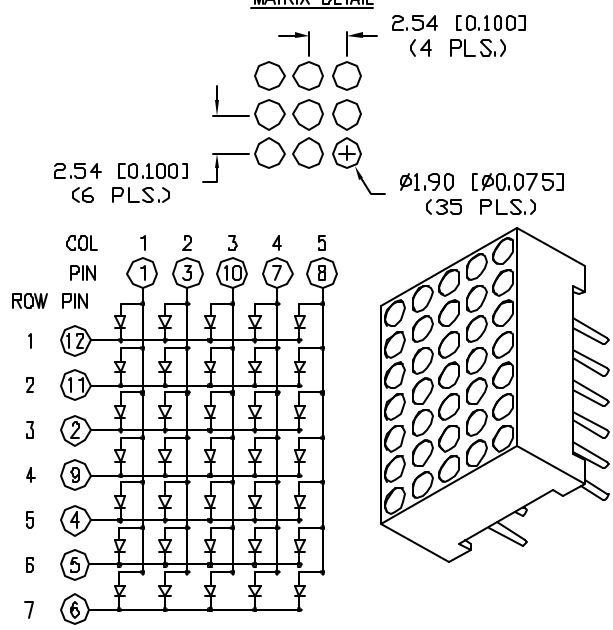
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PART NUMBER
LDM-07557MI

REV.
C



MATRIX DETAIL



COL	1	2	3	4	5
PIN	①	③	⑩	⑦	⑧
ROW	PIN				
1	⑫	↓	↓	↓	↓
2	⑪	↓	↓	↓	↓
3	②	↓	↓	↓	↓
4	⑨	↓	↓	↓	↓
5	④	↓	↓	↓	↓
6	⑤	↓	↓	↓	↓
7	⑥	↓	↓	↓	↓

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR.	7.12.99
B	E.C.N. #10BRDR. & REDRAWN IN 3D.	6.28.03
C	E.C.N. #11148.	03.21.07

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		700		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		500		μcd	$I_f=10\text{mA}$
EMITTED COLOR:	RED				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER DOT

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	120	mW
DERATE FROM 25°C	-1.6	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= ^{+0.00} _{-0.00} DECIMAL PRECISION MAX= ^{+0.00} _{-0.00} DECIMAL PRECISION

REV. C	PART NUMBER LDM-07557MI
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0.70" 5 x 7 DOT MATRIX, LED DISPLAY,
700nm RED DOTS, GRAY FACE WITH WHITE SEGMENTS,
COLUMN ANODE, 12 PINS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JC	CHECKED BY:	APPROVED BY:	DATE: 1.12.93
			PAGE: 1 OF 1
			SCALE: N/A



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